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1796Invention: **AUXILIARY FOR FORMING FINE PATTERN AND PROCESS FOR PRODUCING THE SAME**I hereby certify that this English Language Abstract of JP 10-120968 A - 2 Pages
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(54) RESIN COMPOSITION FOR RESIST PROTECTION FILM, RESIST PROTECTION FILM AND PATTERN PRODUCING METHOD USING THE FILM

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a resin composition for a resist protection film effective for suppressing PED effect and free from absorption band up to ultraviolet range having short wavelength, to provide a resist protection film made of the composition and to provide a process for producing a pattern having high dimensional accuracy in high workability.

SOLUTION: This resin composition for resist protection film and the resist protection film made thereof contain a polyvinylsulfonic acid compound, a water-soluble polymer and water. The pattern-forming process comprises a step to form a resist film on a substrate, a step to expose the resist film in the form of a prescribed pattern and a step to develop the exposed resist. In the above case, a resist protection film is formed on the resist film before the exposure using the composition for resist protection film.

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